# **DB22320**

## Silicon epitaxial planar type

#### For rectification

#### ■ Features

- $\bullet$  Low forward voltage  $V_{\text{F}}$  and small reverse current  $I_{\text{R}}$
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

#### ■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Reverse voltage	V <sub>R</sub>	30	V	
Repetitive peak reverse voltage	V <sub>RRM</sub>	30	V	
Forward current (Average)	I <sub>F(AV)</sub>	1.5	A	
Non-repetitive peak forward surge current *	I <sub>FSM</sub>	30	A	
Junction temperature	T <sub>j</sub>	125	°C	
Storage temperature	T <sub>stg</sub>	-55 to +125	°C	

Note) \*: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

#### ■ Package

• Code

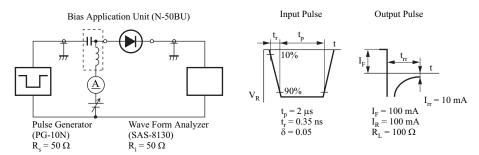
Mini2-F4-B

- Pin Name
  - 1: Cathode
  - 2: Anode
- Marking Symbol: B5

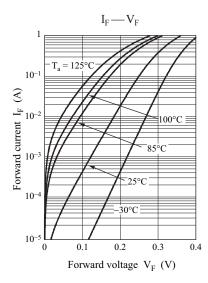
### ■ Electrical Characteristics $T_a = 25$ °C±3°C

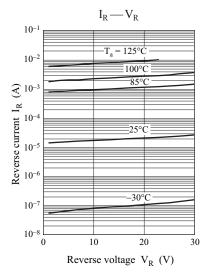
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{F1}$	$I_F = 0.5 A$			0.38	V
	$V_{F2}$	$I_F = 1.0 A$			0.42	
	$V_{F3}$	$I_{\rm F} = 1.5  {\rm A}$			0.46	
Reverse current	$I_R$	$V_R = 30 \text{ V}$			100	μΑ
Terminal capacitance	C <sub>t</sub>	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		48		pF
Reverse recovery time *	t <sub>rr</sub>	$\begin{split} I_F &= I_R = 100 \text{ mA}, \ I_{rr} = 0.1 \times I_R, \\ R_L &= 100 \ \Omega \end{split}$		16		ns

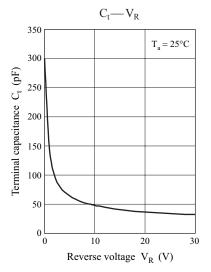
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
  - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
  - 3. \*: t<sub>rr</sub> measurement circuit



DB22320 Panasonic

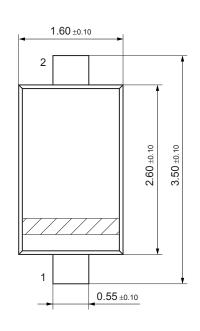


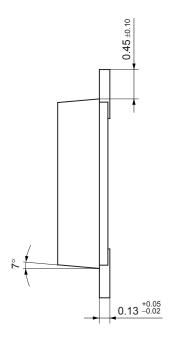


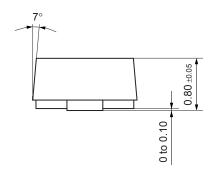


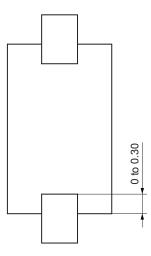
2 Ver. BED

Mini2-F4-B Unit: mm









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